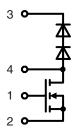
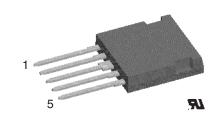


## HiPerFET™ CoolMOS™¹) Power MOSFETs

-Boost Chopper Topologyin ISOPLUS i4-PAC™  $I_{D25}$  = 38 A  $V_{DSS}$  = 600 V  $R_{DSon}$  = 60 m $\Omega$ 





MOSFET				
Symbol	Conditions	Maximum Ratings		
V <sub>DSS</sub>	$T_{VJ} = 25^{\circ}C$ to $150^{\circ}C$	600	V	
$V_{GS}$		±20	V	
I <sub>D25</sub> I <sub>D90</sub>	$T_{c} = 25$ °C $T_{c} = 90$ °C	38 25	A A	

Symbol	Conditions (				
		min.	typ.	max.	
R <sub>DSon</sub>	$V_{GS} = 10 \text{ V}; I_D = 20 \text{ A}$		60	70	mΩ
$V_{GSth}$	$V_{DS} = 20 \text{ V}; I_{D} = 2.7 \text{ mA}$	2.1		3.9	V
I <sub>DSS</sub>	$V_{DS} = V_{DSS}; V_{GS} = 0 \text{ V}; T_{VJ} = 25$ $T_{VJ} = 125$		250	25	μ <b>Α</b> μ <b>Α</b>
I <sub>GSS</sub>	$V_{GS} = \pm 20 \text{ V}; V_{DS} = 0 \text{ V}$			200	nA
Q <sub>g</sub> Q <sub>gs</sub> Q <sub>gd</sub>		A	250 25 120		nC nC nC
t <sub>d(on)</sub> t <sub>r</sub> t <sub>d(off)</sub> t <sub>f</sub>	$\begin{cases} V_{GS} = 10 \text{ V}; V_{DS} = 380 \text{ V}; \\ I_{D} = 47 \text{ A}; R_{G} = 1.8 \Omega \end{cases}$		20 30 110 10		ns ns ns
V <sub>F</sub>	(reverse conduction) I <sub>F</sub> = 20 A;	$V_{GS} = 0 V$	0.9		V
R <sub>thJC</sub> R <sub>thJS</sub>			tbd	0.45	K/W K/W

## **Features**

- fast CoolMOS<sup>™ 1)</sup> power MOSFET 3<sup>rd</sup> generation
  - high blocking voltage
  - low on resistance
- -low thermals resistance due to reduced chip thickness
- HiPerDyn<sup>™</sup> FRED
  - consisting of series connected diodes
  - enhanced dynamic behaviour for high frequency operation
- ISOPLUS i4-PAC™ package
  - isolated back surface
  - low coupling capacity between pins and heatsink
  - enlarged creepage towards heatsink
  - application friendly pinout
  - low inductive current path
  - high reliability
  - industry standard outline
- UL registered, E 72873

## **Applications**

- chopper for power factor correction
- supply of high frequency transformer
  - switched mode power supplies
  - welding converters

¹) CoolMOS™ is a trademark of Infineon Technologies AG.



Free Wheeling Diode (data for series connection)					
Symbol	Conditions	Maximum Ra	Maximum Ratings		
V <sub>RRM</sub>	$T_{VJ} = 25^{\circ}C$ to $150^{\circ}C$	600	V		
I <sub>F25</sub>	$T_C = 25^{\circ}C$ $T_C = 90^{\circ}C$	80 45	A A		

Symbol	Conditions	Characteristic Values min.   typ.   max.			
V <sub>F</sub>	$I_F = 20 \text{ A};  T_{VJ} = 25^{\circ}\text{C}$ $T_{VJ} = 125^{\circ}\text{C}$		2.6 2.0	2.9	V
I <sub>R</sub>	$V_R = V_{RRM}$ ; $T_{VJ} = 25^{\circ}C$ $T_{VJ} = 125^{\circ}C$		0.25	0.25	mA mA
I <sub>RM</sub>	$\begin{cases} I_F = 30 \text{ A; } di_F/dt = -500 \text{ A/}\mu\text{s; } T_{VJ} = 125^{\circ}\text{C} \\ V_R = 300 \text{ V} \end{cases}$		9 40		A ns
${f R}_{ ext{thJC}}$	(per diode)		tbd	0.65	K/W K/W

Component				
Symbol	Conditions	Maximum Ratings		
T <sub>VJ</sub>		-55+150 -55+125	°C	
V <sub>ISOL</sub>	I <sub>ISOL</sub> ≤ 1 mA; 50/60 Hz	2500	٧~	
F <sub>c</sub>	mounting force with clip	20120	N	

Symbol Conditions		Ch	Characteristic Values		
		min.	typ.	max.	
C <sub>P</sub>	coupling capacity between shorted pins and mounting tab in the case		40	pF	
$d_s, d_A$ $d_s, d_A$	pin - pin pin - backside metal	1.7 5.5		mm mm	
Weight			9	g	

